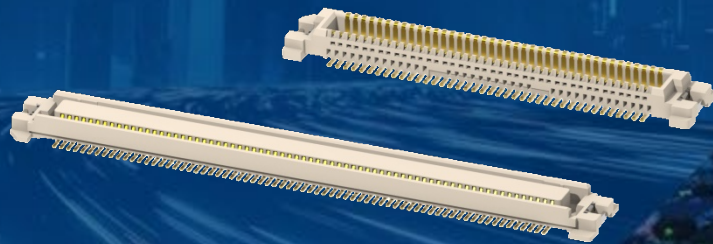


Amphenol

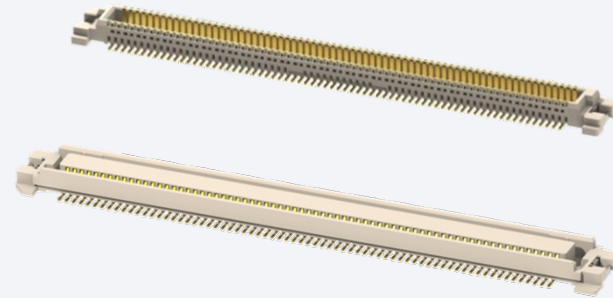
COMMUNICATIONS SOLUTIONS

BergStak[®] 0.635mm Product Presentation



FCi Basics

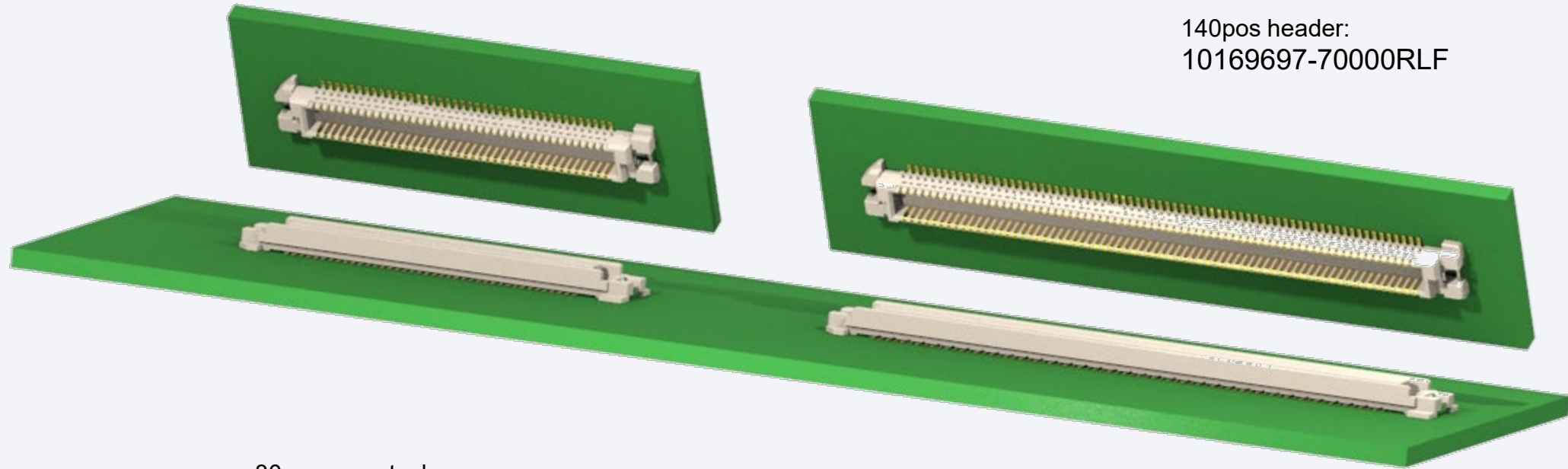
- Value Proposition
- Product Overview
- Product Specifications
- Features & Benefits
- Part Numbers
- Markets & Application



- Amphenol's BergStak® 0.635mm is kind of board to board connector with MICRO PITCH/LOW PROFILE/HIGH PINCOUNT, and it also supports HIGH SPEED data transmission.
- It has golden pitch of 0.635mm, balances requirements for space-saving and robustness, especially suitable for Industrial applications.
- Now the family available in 80 and 140 positions, suitable for applications which require high pin counts and low profile connection.
- Polarization and mis-alignment features to support correct and easier mating.
- The family can reach data rate of 8Gb/s, its open-pin-field design provides design flexibility to customer.
- Vacuum tape to support auto pick/place process.

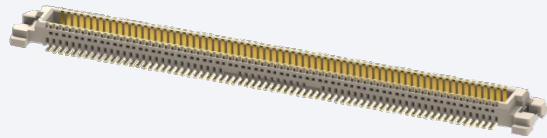
80pos header:
10169697-40000RLF

140pos header:
10169697-70000RLF

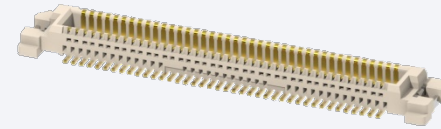


80pos receptacle:
10169698-40000RLF

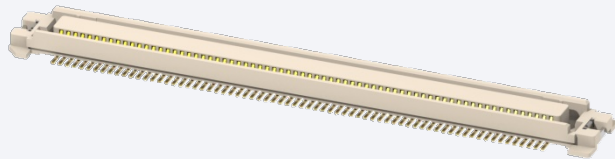
140pos receptacle:
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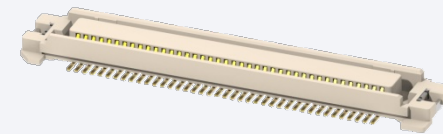
140pos header:
10169697-70000RLF



80pos header:
10169697-40000RLF



140pos receptacle:
10169698-70000RLF



80pos receptacle:
10169698-40000RLF

Product Facts

- Pitch of 0.635mm, double row contacts
- 3mm stack height
- Position of 80 and 140
- Data rate of 8Gb/s

Basic Specifications

Pitch	0.635 mm
Pin Count	80 and 140
PCB Termination	SMT
Conn Direction	Vertical header and receptacle
Plating	Gold flash on contact area

Technical Documents

- Product Spec.: GS-12-1709

Performance Characteristics

- Durability: 50 cycles
- Mating and Un-mating Force: 0.7N max. & 0.12N min./Contact
- Operating Temperature Range: -55° C to +85° C
- Current Rating: 0.5A per contact (all contacts powered)
- Insulation Resistance: 1000MΩ min.
- LLCR: 20mΩ max.
- Mechanical Shock: EIA 364-27
- Vibration: MIL-STD-202, Method 201
- Signal Integrity
 - Data rate: 8Gbps

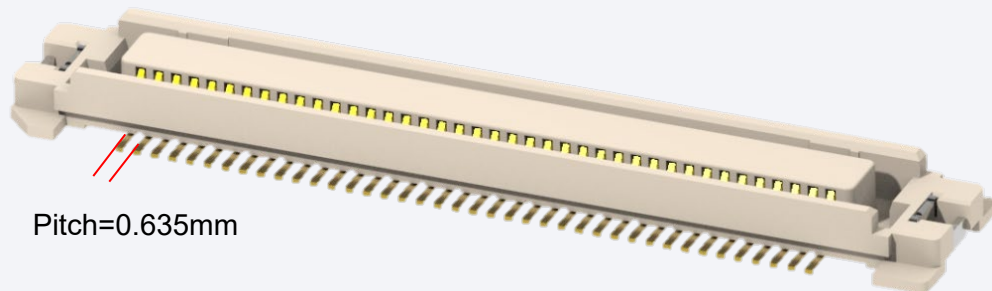
Materials

- Housing: High temperature thermoplastic LCP
- Contact Base Metal
 - Receptacle: Copper Alloy
 - Header: Copper Alloy

Features	Benefits
> Micro Pitch of 0.635mm Low profile design to support 3mm stack height	> High performance, space saving solution.
> High pincounts of 80 and 140	> Applicable for different applications require high pincounts.
> Polarization and mis-alignment features to support correct and easier mating	> Prevents mis-mating and ensures proper mating.
> Side walls to protect contacts	> Avoid deforming risk of contacts while operation.
> High Speed performance of 8 Gb/s with open pin field	> Offers design flexibility for high speed applications.
> Optional vacuum tape	> To support auto-pick/place process.



Low profile design to support 3mm stack height.
High pin counts of 80 and 140 position available.



Pitch=0.635mm

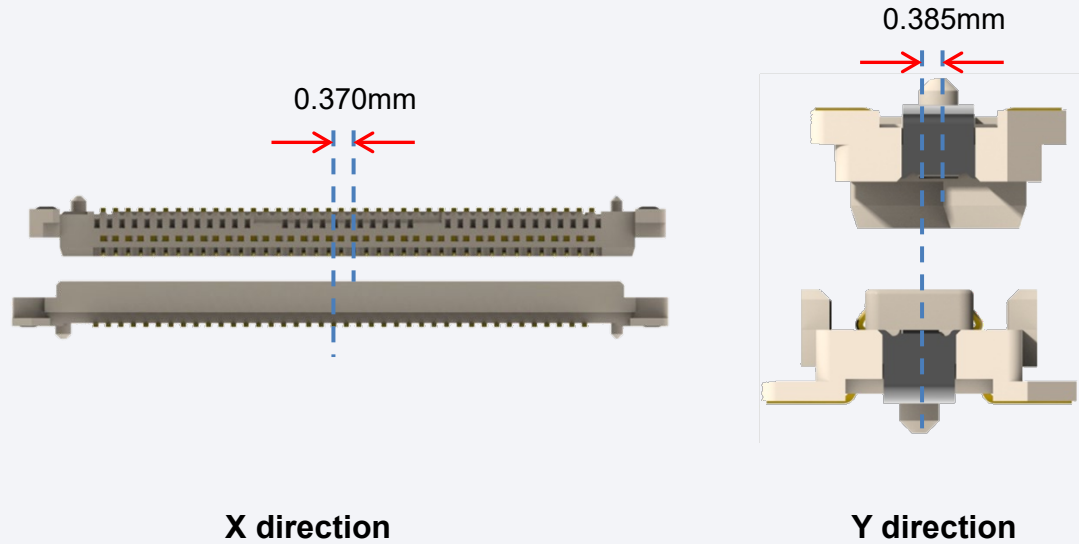
Side wall on housing to protect contacts.



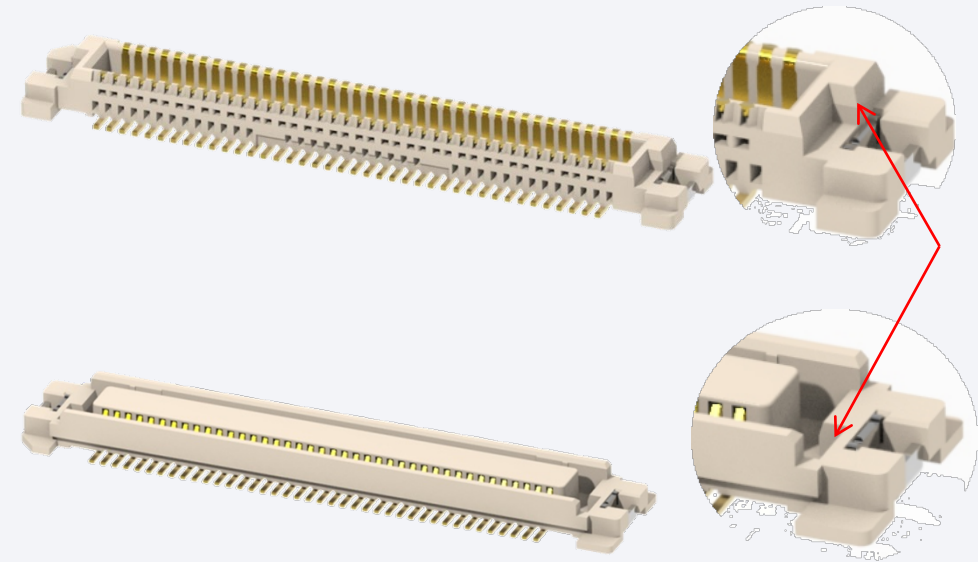
Optional vacuum tape to support auto-pick/place process.

Advanced Features

-Mis-alignment and Polarization feature



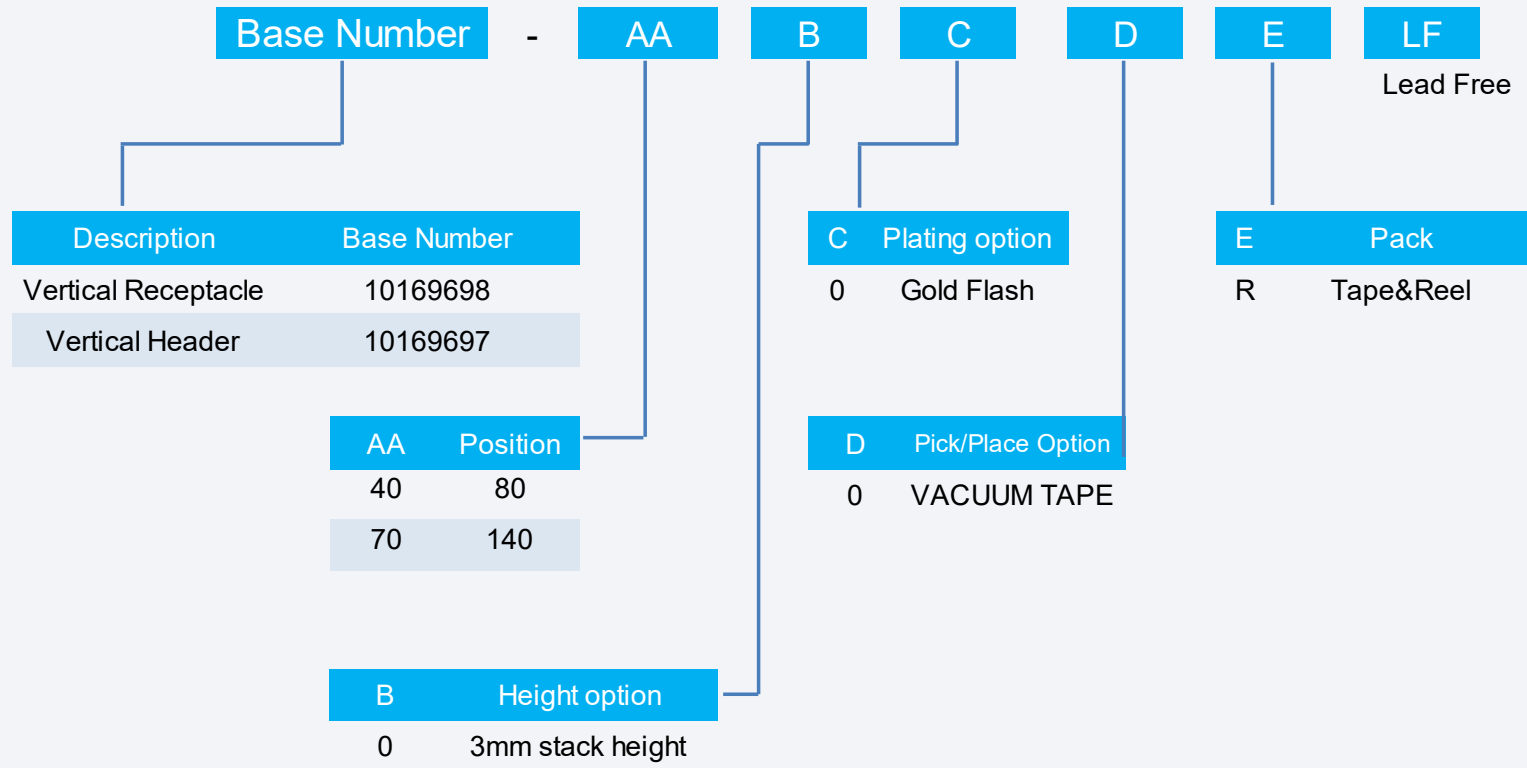
Misalignment tolerance benefit for mating process:
+/-0.370 mm for X direction
+/-0.385 mm for Y direction



Polarization feature to ensure proper mating.

Part Numbers

-Header and receptacle





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